Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously presented) A process of manufacturing, the process comprising forming an electronic device cover member for an electronic device, incorporating electrical circuitry into the cover member during the formation, and providing on the cover member an integral connector structure for connecting the electrical circuitry to an electronic component.

2. (Previously presented) A process according to claim 1, wherein the step of incorporating the electrical circuitry into the cover member comprises forming an electrical circuitry element, arranging the electrical circuitry element in a mould and moulding the cover member onto the electrical circuitry element.

3. (Previously presented) A process according to claim 2, wherein the moulding of the cover member comprises introducing a plastics material into the mould after the electrical circuitry element is arranged in the mould, and forming the connector structure with the cover member in the mould.

4. (Original) A process according to claim 3, wherein the plastics material is introduced into the mould by injection.

5. (Previously presented) A process according to claim 1, wherein the step of incorporating the electrical circuitry

into the cover member comprises forming a first part of the cover member in a first moulding operation, and forming a second part of the cover member in a second moulding operation, the second moulding operation comprising forming a precursor for the electrical circuitry, and thereafter applying an electroconductive material to the precursor to form the electrical circuitry.

6. (Original) A process according to claim 5, wherein the integral connector structure is formed on the second part during the second moulding operation.

7. (Original) A process according to claim 5, wherein the first moulding operation comprises introducing a first plastics material into the first part of the mould.

8. (Original) A process according to claim 5, wherein electroconductive material is a metallic material.

9. (Original) A process according to claim 5, wherein a step of applying the electroconductive material comprises plating the electroconductive material onto the precursor.

10. (Original) A process according to claim 9, wherein the step of plating the electroconductive material consists of one or both selected from electroplating and electroless plating.

11. (Original) A process according to claim 9, wherein the second moulding operation comprises introducing a second plastics material into the mould, the second plastics material carrying a seeding substance to seed the plating of the electroconductive material onto the precursor, the seeding substance comprising metallic particles.

12. (Previously presented) A process according to claim 1, wherein the step of incorporating the electrical circuitry into the cover member comprises providing a substrate, forming a precursor for the electrical circuitry on the substrate, moulding the substrate to form the cover member and then applying an electroconductive material to the precursor to form the electrical circuitry.

13. (Original) A process according to claim 12, wherein the step of applying the electroconductive material comprises plating the electroconductive material onto the precursor.

14. (Original) A process according to claim 13, wherein the step of plating the electroconductive material consists of one or both selected from electroplating and electroless plating.

15. (Original) A process according to claim 13, wherein the step of forming the precursor comprises applying a carrier material to the substrate, the carrier material carrying a seeding substance to seed the plating of the electroconductive material onto the precursor, the secondary substance comprising metallic particles.

16. (Original) A process according to claim 15, wherein the carrier material comprises an ink and the step of applying the carrier material to the substrate comprises printing the carrier material on the substrate.

17. (Previously presented) A process according to claim 12, wherein the substrate comprises a plastics material and the step of moulding the substrate to form the cover member comprises vacuum or press moulding the substrate.

18. (Previously presented) A process according to claim 12, wherein the step of providing the connector structure on the cover member comprises moulding the connector onto the cover member after the substrate has been moulded to form the cover member.

19. (Original) A process according to claim 1 comprising providing a flexible holding member in the connector structure to hold the electronic component in electrical communication with the electrical circuitry.

20. (Original) A process according to claim 19, wherein the flexible holding member comprises a resilient member.

21-32. (Cancelled)

33. (Previously presented) A process of manufacturing an electronic device cover, the process comprising:

forming an electronic device cover member;

incorporating electrical circuitry into the cover member during the forming of the cover member; and

providing on the cover member a connector structure for connecting the electrical circuitry to an electronic component, wherein the connector structure is integrally formed with the cover member during the incorporating of the electrical circuitry into the cover member during the forming of the cover member.

34. (New) A process as in claim 1 wherein forming the electronic device cover member for an electronic device comprises forming a mobile phone cover member, wherein the

electrical circuitry is incorporated into the mobile phone cover member during the formation of the mobile phone cover member, and wherein the mobile phone cover member comprises the integral connector structure.

35. (New) A process as in claim 33 wherein forming the electronic device cover member comprises forming a mobile phone cover member, wherein the electrical circuitry is incorporated into the mobile phone cover member during forming of the mobile phone cover member, and wherein the connector structure is integrally formed with the mobile phone cover member.